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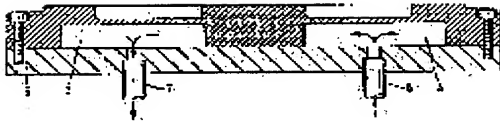
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**(54) APPARATUS FOR COATING SURFACE OF ELECTROSTATIC CHUCK
WITH LAYER OF DIELECTRIC SUBSTANCE**

(57)Abstract:

PURPOSE: To provide an electrostatic wafer chuck which is strictly controlled exerting a preliminarily set attraction force when a voltage is applied, by circulating a coolant through a recessed part at a rear face of the chuck during an anodic oxidation process.



CONSTITUTION: A closed back plate is replaceable with a back plate 5 which has an opening to allow a fluid coolant to enter from an injection opening 6 and come out of a discharge opening through an enclosed recessed part 3. A chuck is kept at a uniform temperature in its entirety during an anodic oxidation process, so that a uniform plating (anodic oxidation) thickness is ensured all over a surface of the chuck. Accordingly, an electrostatic attraction force acting between a wafer and the chuck can be controlled in size better.

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